

AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Wei Pan, David R. Evans and Sheng Teng Hsu			Docket No. SLA0499		
Serial No 09/978,434	Filing Date October 16, 2001	Examiner Timothy H. Meeks	Group Art Unit 1762		
Invention: Method of controlling the Initial Growth of CVD Copper Films by Surface Treatment of Barrier Metals Films					
<u>TO THE COMMISSIONER FOR PATENTS:</u>					
Transmitted herewith is an amendment in the above identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER OF EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	7 -	20 =	0	x \$18.00	\$0.00
INDEP. CLAIMS	2 -	4 =	0	x \$84.00	\$0.00
Multiple Dependent Claims (check if applicable) _____					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

☒ No additional fee is required for amendment.
☐ Please charge Deposit Account No. 19-1457 in the amount of \$0.00.
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☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-1457.
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☒ Any additional fees required under 37 C.F.R. 1.16.
☒ Any patent application processing fees under 37 C.F.R. 1.17.

_____ Dated: SEPTEMBER 2, 2003
 David C. Ripma, Reg. No. 27,672

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office under 37 C.F.R. §1.8 at Fax No. (703) 872-9310 on September 2, 2003.

 David C. Ripma, Reg. No. 27,672

Note: Each paper must have its own certificate or transmission, or this certificate must identify each submitted paper. The papers submitted include:

<input checked="" type="checkbox"/> This Amendment Transmittal Letter (Duplicate Attached)	2 page(s)
<input checked="" type="checkbox"/> Response under 37 CFR § 1.111	4 page(s)
<input type="checkbox"/> Attachments	page(s)
<input type="checkbox"/> Petition for Extension of Time under 37 C.F.R. § 1.136	page

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Total pages, including this Transmittal: 6

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/978,434
Applicant: Wei Pan et al.
Filed: October 16, 2001
Group #: 1762
Examiner: Timothy H. Meeks

Confirmation Number: 5020

Docket No: SLA.0499
Customer No: 27518
For: Method of Controlling the Initial Growth of CVD Copper Films by Surface
Treatment of Barrier Metals Films

MS Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

RESPONSE TO OFFICE ACTION UNDER 37 C.F.R. § 1.111
Introductory Comments

In response to the Office Action dated June 2, 2003, please amend the above-identified Application as follows:

Amendment to the Specification, None

Amendment to the Claims are reflected in the listing of claims which begins on page 2, of this paper.

Amendment to the Drawings, None

Remarks/Arguments begin on page 4 of this paper.

An Appendix is not included.

Page 1 Response to Office Action under 37 C.F.R. § 1.111 for Serial No. 09/978,434